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Invited Talk 1:

2019 Mar 19, 9:10 – 9: 40

Chair: Akio Higo, *The University of Tokyo, Japan*

9:00 **Electronic photonic IC technology - challenges of on-wafer characterization and test**
Invited1 [Invited] ……………………………………………………………………………N/A
Lars Zimmermann, *IHP – Leibniz-Insitut für innovative Mikroelektronik, Germany*

Session 1: Photonic Test Structures

2019 Mar 19, 9:40 – 11: 00

Co-Chairs: Alexey Kovalgin, *University of Twente, The Netherland*

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[1]*VLSI Design and Education Center, The University of Tokyo, Japan*
[2]*Graduate School of Engineering, The University of Tokyo, Japan*
[3]*Yokohama National University, Japan*

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[1]*Research Center for Advanced Science and Technology, The University of Tokyo, Japan*
[2]*VLSI Design and Education Center, The University of Tokyo, Japan*
[3]*Graduate School of Engineering, The University of Tokyo, Japan*
[4]*Graduate School of Art and Science, the University of Tokyo, Japan*

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[1]*MESA+ Institute for Nanotechnology, University of Twente, The Netherlands*
[2]*Department of Materials and Production, Aalborg University, Denmark*

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Department of Silicon Photonics Test Development, GLOBALFOUNDRIES

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2019 Mar 19, 11:20 – 12:20

Co-Chairs: Larg Weiland, *PDF Solutions, USA*
Shigetaka Mori, *SONY Corporation, Japan*

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[1]*Department of Electrical Engineering, Faculty of Science and Technology, Tokyo University of Science, Japan*
[2]*Department of Electronics, Graduate School of Science and Technology, Kyoto Institute of Technology, Japan*

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[1] *STMicroelectronics, France*
[2] *IMS, Université Bordeaux I, France*

Invited Talk 2:

2019 Mar 19, 13:35 – 14:05

Chair: Tsuyoshi Sekitani, *Osaka University, Japan*

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Research Network and Facility Services Division, National Institute for Materials Science (NIMS), Japan

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Co-Chairs: Chadwin Young*, University of Texas at Dallas*

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[2]*VLSI Design and Education Center, The University of Tokyo, Japan*

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[1]*School of Engineering, Institute for Integrated Micro and Nano Systems, The University of Edinburgh, UK*
[2]*School of Engineering, Institute for Bioengineering, The University of Edinburgh, UK*

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[1]*Graduate School of Engineering, Tohoku University, Japan*
[2]*School of Engineering, Tohoku University, Japan*
[3]*New Industry Creation Hatchery Center, Tohoku University, Japan*

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[1]*Samsung Austin Semiconductor, LLC, USA*
[2]*Materials Science and Engineering Department, University of Texas at Dallas, USA*

Invited Talk 3:

2019 Mar 20, 09:00 – 09:30

Chair: Yoshio Mita, *The University of Tokyo, Japan*

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[1]*Department of Electrical and Computer Engineering, University of California, Santa Barbara, U.S.A.*
[2]*Instituto de Investigación en Comunicación Óptica, FC, Universidad Autónoma de San Luis Potosí, México*
[3]*School of Engineering, Hong Kong University of Science and Technology, Hong Kong*

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Co-Chairs: Tatsuya Ohguro, *Toshiba, Japan*

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and T. Hiramoto[1]
[1]*Institute of Industrial Science, the University of Tokyo, Japan*
[2]*Meiji University, Japan*, [3]*Tokyo Institute of Technology, Japan*
[4]*Green Electronics Research Institute, Japan*, [5]*Kyushu University, Japan,*
[6]*Kyushu Institute of Technology, Japan*

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[1]*Faculty of Engineering, Kyoto University, Japan*
[2]*Graduate School of Science and Technology, Nara Institute of Science and Technology, Japan*
[3]*Graduate School of Informatics, Kyoto University, Japan*

SESSION 6: Matching & Variability

2019 Mar 20 10:50 – 12:10

Co-Chairs: Hans P. Tuinhout, *NXP Semiconductor, The Netherlands*
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Co-Chairs: Francesco Driussi, *University of Udine – DPIA, Italy*
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[1] *IMS Laboratory, University of Bordeaux, France*
[2] *IHP – Leibniz-Insitut für innovative Mikroelektronik, Germany*

SESSION 8: Noise

2019 Mar 20 15:30 – 16:30

Co-Chairs: Kiyoshi Takeuchi*, The University of Tokyo, Japan*
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[1]*Graduate School of Engineering, Kyoto University, Japan*

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[1]*Saginomiya Seisakusho, Inc., Japan*

[2]*Institute of Industrial Science, The university of Tokyo, Japan*

[3]*Shizuoka University, Japan*

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Co-Chairs: Satoshi Habu, *Keysight, Japan*

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[1]*STMicroelectronics Rousset, France*, [2]*LTM CNRS, France*

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[1]*School of Electrical Engineering, The University of Tokyo*

[2]*VLSI Design & Education Center (VDEC), The University of Tokyo*

[3]*NEXTY Electronics Corporation*

SESSION 10: TFTs

2019 Mar 21 10:40 – 11:20

Co-Chairs: Yoshio Mita, *The University of Tokyo, Japan*

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[1]*Graduate School of Informatics, Kyoto University, Japan*

[2]*Graduate School of Science and Technology, Nara Institute of Science and Technology, Japan*

[3]*National Institute of Advanced Industrial Science and Technology (AIST), Japan*